0.5085 mm

5.5878 mm

40.0000 mm

48.0000 mm

14.3400 mm

25.0000 mm

33.0000 mm

| Layer Name | Type | Material | Thickness (mm) | Color | Epsilon R | Loss Tangent |
|---|---|---|---|---|---|---|
| F.Silkscreen | Top Silk Screen | Not specified | 0 mm | Not specified | 1 | 0 |
| F.Paste | Top Solder Paste | | 0 mm | | 1 | 0 |
| F.Mask | Top Solder Mask | Not specified | 0.01 mm | Not specified | 3.3 | 0 |
| F.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | core | FR4 | 1.51 mm | | 4.5 | 0.02 |
| B.Cu | copper | | 0.035 mm | | 1 | 0 |
| B.Mask | Bottom Solder Mask | Not specified | 0.01 mm | Not specified | 3.3 | 0 |
| B.Paste | Bottom Solder Paste | | 0 mm | | 1 | 0 |
| B.Silkscreen | Bottom Silk Screen | Not specified | 0 mm | Not specified | 1 | 0 |

## BOARD CHARACTERISTICS

Copper Layer Count:        2                               Board Thickness:        1.6000 mm

Board overall dimensions:  0.0000 mm x 0.0000 mm

Min track/spacing:         0.2000 mm / 0.0000 mm    Min hole diameter:      0.3000 mm

Copper Finish:             None                         Impedance Control:      No

Castellated pads:          No                           Plated Board Edge:      No

Edge card connectors:      No